# **MOSFET** - Power, Single **N-Channel** 60 V, 26.5 mΩ, 20 A

#### **Features**

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

## **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltag	$V_{DSS}$	60	V		
Gate-to-Source Voltage	9		V <sub>GS</sub>	±20	V
Continuous Drain		T <sub>C</sub> = 25°C	I <sub>D</sub>	20	Α
Current R <sub>θJC</sub> (Notes 1, 2, 3, 4)	Steady	T <sub>C</sub> = 100°C		14	
Power Dissipation	State	T <sub>C</sub> = 25°C	$P_{D}$	20	W
R <sub>θJC</sub> (Notes 1, 2, 3)		T <sub>C</sub> = 100°C		10	
Continuous Drain		T <sub>A</sub> = 25°C	I <sub>D</sub>	7.82	Α
Current R <sub>0JA</sub> (Notes 1, 3, 4)	Steady State	T <sub>A</sub> = 100°C		6.54	
Power Dissipation		T <sub>A</sub> = 25°C	$P_{D}$	3.0	W
R <sub>θJA</sub> (Notes 1, 3)		T <sub>A</sub> = 100°C		2.1	
Pulsed Drain Current	Pulsed Drain Current $T_A = 25^{\circ}C$ , $t_p = 10 \mu s$			80	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body D	Is	17	Α		
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 1 A)			E <sub>AS</sub>	51	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 3)	$R_{ heta JC}$	7.32	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	49	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi  $(\Psi)$  is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- 4. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

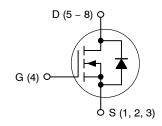


## ON Semiconductor®

#### www.onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX	
60 V	26.5 mΩ @ 10 V	20 A	
	42.5 mΩ @ 4.5 V	2014	

#### N-Channel







sd Ьο S AYWW= S Gΰ Дο

**MARKING DIAGRAM** 

XXXX = Specific Device Code Α = Assembly Location

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•					•	•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu A$		60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 \text{ V},$ $T_J = 25^{\circ}\text{C}$				10	μΑ
		V <sub>DS</sub> = 60 V	T <sub>J</sub> = 125°C			100	1
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{G}$	<sub>S</sub> = +20 V			100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{E}$	ο = 13 μΑ	1.2		2.2	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I	<sub>D</sub> = 10 A		22	26.5	mΩ
		V <sub>GS</sub> = 4.5 V,	I <sub>D</sub> = 10 A		34	42.5	1
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 15 V, I	<sub>D</sub> = 10 A		20		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, f =			327		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 2	5 V		161		_
Reverse Transfer Capacitance	C <sub>rss</sub>				6.0		
Total Gate Charge	Q <sub>G(TOT)</sub>				2.9		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	1,, ,,,,,	40.1/ 1 40.4		0.8		nC
Gate-to-Source Charge	$Q_{GS}$	$V_{GS} = 4.5 \text{ V}, V_{DS} = 48 \text{ V}, I_D = 10 \text{ A}$			1.2		1
Gate-to-Drain Charge	$Q_{GD}$				8.0		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> =	48 V, I <sub>D</sub> = 10 A		6.0		nC
SWITCHING CHARACTERISTICS (No	ote 6)						
Turn-On Delay Time	t <sub>d(on)</sub>				6.5		ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V	<sub>DS</sub> = 48 V,		25		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS} = 4.5 \text{ V, V}_{D}$	$\frac{1}{3} = 1.0 \Omega$		13		1
Fall Time	t <sub>f</sub>	1			23		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0 V$ ,	T <sub>J</sub> = 25°C		0.9	1.2	V
		I <sub>S</sub> = 10 A	T <sub>J</sub> = 125°C		0.8		1
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ A}$			17		ns
Charge Time	t <sub>a</sub>				8.0		1
Discharge Time	t <sub>b</sub>				9.0		1
Reverse Recovery Charge	$Q_{RR}$				7.0		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**

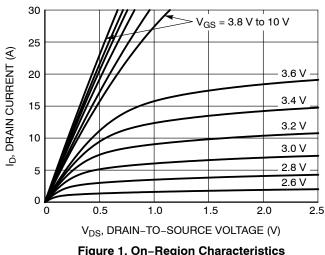


Figure 1. On-Region Characteristics

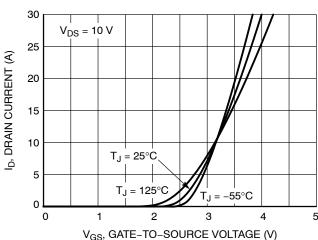


Figure 2. Transfer Characteristics

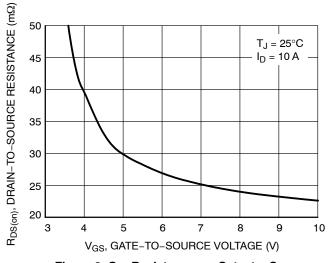


Figure 3. On-Resistance vs. Gate-to-Source Voltage

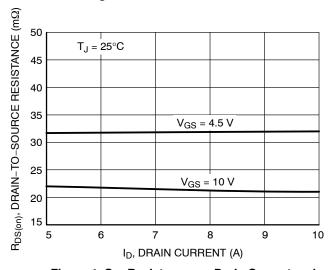


Figure 4. On-Resistance vs. Drain Current and **Gate Voltage** 

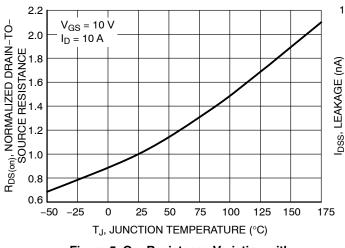


Figure 5. On-Resistance Variation with **Temperature** 

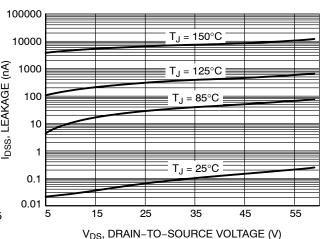


Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### **TYPICAL CHARACTERISTICS**

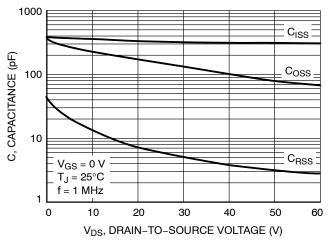


Figure 7. Capacitance Variation

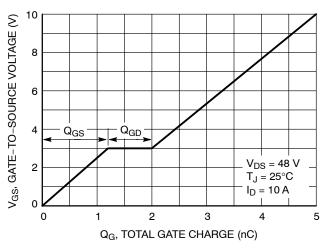


Figure 8. Gate-to-Source vs. Total Charge

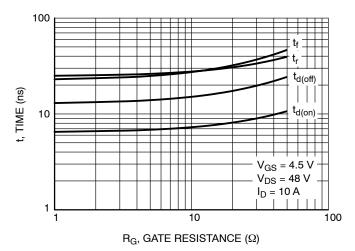


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

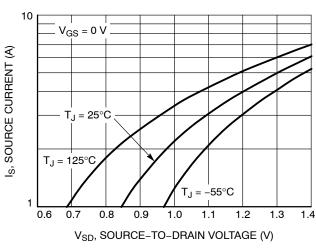


Figure 10. Diode Forward Voltage vs. Current

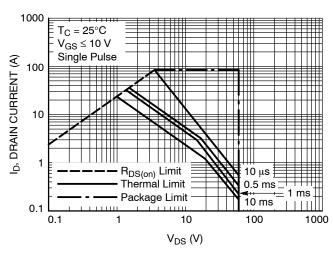


Figure 11. Maximum Rated Forward Biased Safe Operating Area

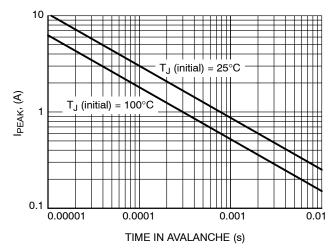


Figure 12. I<sub>PEAK</sub> vs. Time in Avalanche

#### **TYPICAL CHARACTERISTICS**

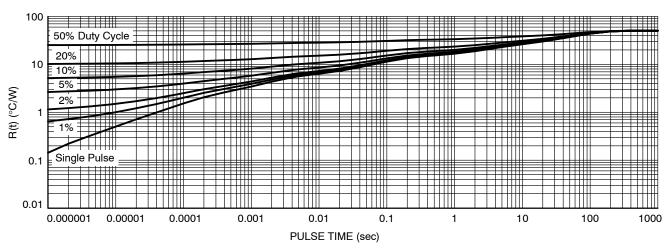


Figure 13. Thermal Characteristics

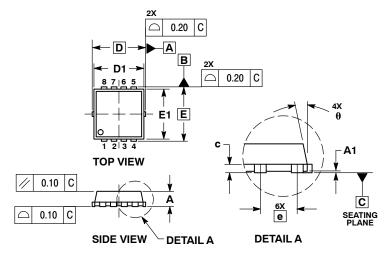
## **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NTTFS5C680NLTAG	680L	WDFN8 (Pb-Free)	1500 / Tape & Reel
NTTFS5C680NLWFTAG	80LW	WDFN8 (Pb-Free)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

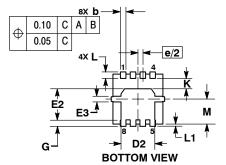
#### WDFN8 3.3x3.3, 0.65P CASE 511AB ISSUE D



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D		3.30 BSC		0.130 BSC			
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E	3.30 BSC			0	.130 BSC		
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е	0.65 BSC			0.026 BSC			
G	0.30	0.41	0.51	0.012	0.016	0.020	
K	0.65	0.80	0.95	0.026	0.032	0.037	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
M	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	



# **SOLDERING FOOTPRINT\*** -0.66 ĊН PACKAGE OUTLINE 3.60 2. 0.75 0.57 2.37 3.46

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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